

SLOVENSKI STANDARD

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Nadomešča:
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Tehnologija površinske montaže - 4. del: Razvrščanje, pakiranje, etiketiranje in ravnanje z napravami, občutljivimi na vlago

Surface mounting technology - Part 4: Classification, packaging, labelling and handling of moisture sensitive devices

Oberflächenmontagetechnik - Teil 4: Genormtes Verfahren zur Klassifikation, Verpackung, Kennzeichnung und Handhabung feuchteempfindlicher Bauteile

Technique du montage en surface - Partie 4: Classification, emballage, étiquetage et manipulation des dispositifs sensibles à l'humidité

Ta slovenski standard je istoveten z: EN IEC 61760-4:2026

ICS:

31.190	Sestavljeni elektronski elementi	Electronic component assemblies
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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 61760-4

July 2026

ICS 31.190

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English Version

**Surface mounting technology - Part 4: Classification, packaging,
labelling and handling of moisture sensitive devices
(IEC 61760-4:2026)**

Technologie de montage en surface - Partie 4:
Classification, emballage, étiquetage et manipulation des
dispositifs sensibles à l'humidité
(IEC 61760-4:2026)

Oberflächenmontagetechnik - Teil 4: Genormtes Verfahren
zur Klassifikation, Verpackung, Kennzeichnung und
Handhabung feuchteempfindlicher Bauteile
(IEC 61760-4:2026)

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EN IEC 61760-4:2026 (E)**European foreword**

The text of document 91/2101/FDIS, future edition 2 of IEC 61760-4, prepared by TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61760-4:2026.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2027-07-31 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2029-07-31 document have to be withdrawn

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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 60749-20	NOTE	Approved as EN IEC 60749-20
IEC 60068-2-78	NOTE	Approved as EN IEC 60068-2-78
IEC 60068-2-58:2015	NOTE	Approved as EN 60068-2-58:2015 (not modified)
IEC 60068-2-58	NOTE	Approved as EN 60068-2-58
ISO 62	NOTE	Approved as EN ISO 62
IEC 61760-2	NOTE	Approved as EN IEC 61760-2
IEC 61340-5-1	NOTE	Approved as EN IEC 61340-5-1

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	2013	Environmental testing - Part 1: General and guidance	EN 60068-1	2014

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Edition 2.0 2026-05

INTERNATIONAL STANDARD

**Surface mounting technology -
Part 4: Classification, packaging, labelling and handling of moisture sensitive
devices**

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